Title (en)
METHOD AND SYSTEM FOR EMBEDDED TEMPERATURE AND/OR STRAIN SENSORS

Title (de)
VERFAHREN UND SYSTEM FÜR EINGEBETTETE TEMPERATUR- UND/ODER DEHNUNGSSENSOREN

Title (fr)
PROCÉDÉ ET SYSTÈME DESTINÉS À DES CAPTEURS DE TEMPÉRATURE ET/OU DE CONTRAINTE INCORPORÉS

Publication
EP 2710797 B1 20180411 (EN)

Application
EP 12725928 A 20120515

Priority
- US 201161486761 P 20110516
- US 201213467111 A 20120509
- US 201213467139 A 20120509
- US 2012037922 W 20120515

Abstract (en)
[origin: US2012293646A1] A system and method for monitoring system including a embedded sensor coupled to an article, wherein the embedded sensor is a direct write embedded sensor using a high temperature light emitting material. A camera system detects illumination signals from the embedded sensors. A processing section processes the illumination signals and determines gas/surface temperatures and strain data for the article.

IPC 8 full level
H04N 5/30 (2006.01); **B23P 15/00** (2006.01); **B23P 17/00** (2006.01); **H04N 7/18** (2006.01)

CPC (source: EP RU US)
F01D 17/02 (2013.01 - EP US); **G01B 11/165** (2013.01 - US); **G01D 5/34** (2013.01 - EP US); **G01K 11/20** (2013.01 - EP US); **G01K 13/02** (2013.01 - EP US); **G01K 13/024** (2021.01 - EP RU); **G01L 23/16** (2013.01 - EP US); **G06T 7/001** (2013.01 - EP US); F05D 2260/80 (2013.01 - EP US); G01D 5/34 (2013.01 - RU); G01K 13/024 (2021.01 - US); G01L 23/16 (2013.01 - RU); G06T 2207/30164 (2013.01 - EP US); Y02T 50/60 (2013.01 - US); Y10T 29/49117 (2015.01 - EP US); Y10T 29/49124 (2015.01 - EP US); Y10T 29/49336 (2015.01 - EP US); Y10T 29/49769 (2015.01 - EP US)

Citation (examination)
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US 2012293646 A1 20121122; **US 9551620 B2 20170124**; CN 103703351 A 20140402; CN 103703351 B 20160113; EP 2710797 A2 20140326; EP 2710797 B1 20180411; JP 2014519601 A 20140814; JP 5977820 B2 20160824; RU 2013148906 A 20150627; RU 2610693 C2 20170214; US 2012293647 A1 20121122; US 9482585 B2 20161101; WO 2012158681 A2 20121122; WO 2012158681 A3 20130411

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